DSB (Double Sided PCB) Fabrication Process Flow

Highlighted processes will be handled separately

NC Drill Data

- Shearing Machine
  - Cut Copper Clad Laminate (CCL) to Size

- CNC Drilling Machine
  - Drill CCL as per drill drawing from design

- Brushing Machine
  - Debur drilled holes

- Electroless Plating Machine
  - Clean & Prepare the drilled holes for Electro Plating

- Electro-Plating Machine
  - Electroplate the drilled holes with Copper

- Brushing Machine
  - Brush the platted CCL for removing any blemishes

- Dry Film Laminator
  - Laminate the CCL with Dry Film Resist (DFR)

- UV Exposure Machine
  - Expose the CCL for the required pattern

- Developing Machine
  - Develop the etch resist for required pattern

- Electroplating Machine
  - Electroplate the pattern and holes with Tin

- Stripping of DFR
  - Remove unwanted dry film resist from CCL
Etching Machine
– Etch the unwanted copper from CCL

Electroplating Machine
– Strip the unwanted Tin from the pattern etched

Screen Printing Jig
– Coat the PCB with LPI Solder Mask Ink

Hot Air Oven
– Bake the PCB

UV Exposure Machine
– Exposed the solder mask pattern on PCB

Developing Machine
– Develop the solder mask pattern on PCB

Hot Air Oven
– Cure solder mask pattern on PCB

CNC Drilling Machine / Shearing Machine
– De-panel the PCB

Screen Printing Jig
– Print the PCB with Marking Ink

Hot Air Oven
– Cure marking ink on PCB

Electroplating Machine
– Coat the PCB with Anti-tarnish Liquid